

ABSTRACT

5 A technique capable of stabilizing pressure control of a polishing head when a
polishing rate changes significantly during polishing of a workpiece, such as a wafer, is
disclosed. A polishing method includes during polishing of the workpiece, calculating a
plurality of polishing rates of a plurality of regions within the surface of the workpiece; and
detecting a plurality of change points of the plurality of polishing rates. Before the
10 plurality of change points of the plurality of polishing rates are detected, the polishing head
performs a polishing-amount control operation of polishing the plurality of regions of the
workpiece by the same polishing amount. After the plurality of change points of the
plurality of polishing rates are detected, the polishing head performs a profile control
operation of polishing the plurality of regions of the workpiece such that a film-thickness
15 profile of the workpiece reaches a target film-thickness profile.

FIG. 5